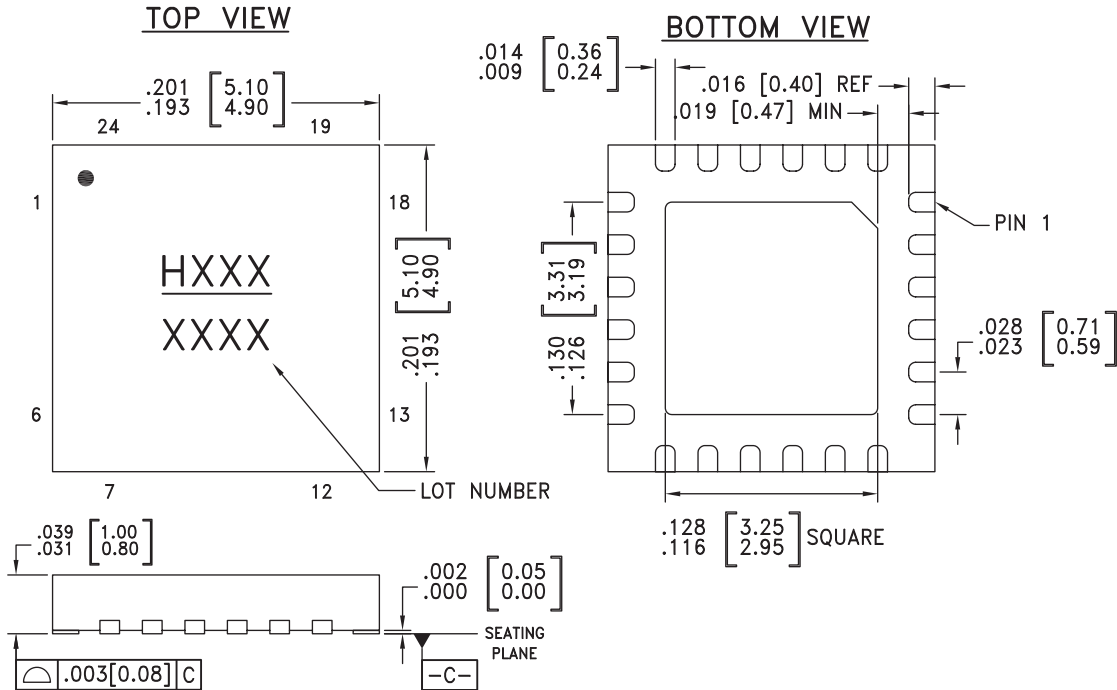


LP5G (E) – 5 x 5 mm QUAD FLATPACK NO-LEAD (QFN) PLASTIC PACKAGE

LP5G (E) Package Outline Drawing



NOTES:

- PACKAGE BODY MATERIAL: LOW STRESS INJECTION MOLDED PLASTIC SILICA AND SILICON IMPREGNATED.
- LEAD AND GROUND PADDLE MATERIAL: COPPER ALLOY.
- LEAD AND GROUND PADDLE PLATING: 100% MATTE TIN.
- DIMENSIONS ARE IN INCHES [MILLIMETERS].
- LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- PAD BURR LENGTH SHALL BE 0.15mm MAX. PAD BURR HEIGHT SHALL BE 0.25mm MAX.
- PACKAGE WARP SHALL NOT EXCEED 0.05mm
- ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED PCB LAND PATTERN.

Package Information

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking ^{[3][4]}
LP5G	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 ^[1]	HNNN XXXX
LP5GE	RoHS Compliant Mold Compound	100% matte Sn	MSL1 ^[2]	HNNN XXXX

[1] Max peak reflow temperature of 235 °C

[2] Max peak reflow temperature of 260 °C

[3] 4-Digit lot number XXXX

[4] 3-Digit part number NNN